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Multiformat Video Encoder, Six 12-Bit *Noise Shaped Video DACs*

Data Sheet

ADV7340/ADV7341

FEATURES

74.25 MHz 20-/30-bit high definition input support

Compliant with SMPTE 274 M (1080i), 296 M (720p),
and 240 M (1035i)

6 *Noise Shaped Video*® (NSV) 12-bit video DACs

16× (216 MHz) DAC oversampling for SD

8× (216 MHz) DAC oversampling for ED

4× (297 MHz) DAC oversampling for HD

37 mA maximum DAC output current

NTSC M, PAL B/D/G/H/I/M/N, PAL 60 support

NTSC and PAL square pixel operation (24.54 MHz/29.5 MHz)

Multiformat video input support

4:2:2 YCrCb (SD, ED, and HD)

4:4:4 YCrCb (ED and HD)

4:4:4 RGB (SD, ED, and HD)

Multiformat video output support

Composite (CVBS) and S-Video (Y-C)

Component YPrPb (SD, ED, and HD)

Component RGB (SD, ED, and HD)

Macrovision Rev 7.1.L1 (SD) and Rev 1.2 (ED) compliant

Simultaneous SD and ED/HD operation

EIA/CEA-861B compliance support

Copy generation management system (CGMS)

Closed captioning and wide screen signaling (WSS)

Integrated subcarrier locking to external video source

Complete on-chip video timing generator

On-chip test pattern generation

On-board voltage reference (optional external input)

Programmable features

Luma and chroma filter responses

Vertical blanking interval (VBI)

Subcarrier frequency (F_{sc}) and phase

Luma delay

High definition (HD) programmable features

(720p/1080i/1035i)

4× oversampling (297 MHz)

Internal test pattern generator

Fully programmable YCrCb to RGB matrix

Gamma correction

Programmable adaptive filter control

Programmable sharpness filter control

CGMS (720p/1080i) and CGMS Type B (720p/1080i)

Undershoot limiter

Dual data rate (DDR) input support

Enhanced definition (ED) programmable features

(525p/625p)

8× oversampling (216 MHz output)

Internal test pattern generator

Black bar, hatch, flat field/frame

Individual Y and PrPb output delay

Gamma correction

Programmable adaptive filter control

Fully programmable YCrCb to RGB matrix

Undershoot limiter

Macrovision Rev 1.2 (525p/625p) (ADV7340 only)

CGMS (525p/625p) and CGMS Type B (525p)

Dual data rate (DDR) input support

Standard definition (SD) programmable features

16× oversampling (216 MHz)

Internal test pattern generator

Color and black bar

Controlled edge rates for start and end of active video

Individual Y and PrPb output delay

Undershoot limiter

Gamma correction

Digital noise reduction (DNR)

Multiple chroma and luma filters

Luma-SSAF filter with programmable gain/attenuation

PrPb SSAF

Separate pedestal control on component and
composite/S-Video output

VCR FF/RW sync mode

Macrovision Rev 7.1.L1 (ADV7340 only)

Copy generation management system (CGMS)

Wide screen signaling (WSS)

Closed captioning

Serial MPU interface with I²C compatibility

3.3 V analog operation

1.8 V digital operation

1.8 V or 3.3 V I/O operation

Temperature range: -40°C to +85°C

APPLICATIONS

DVD recorders and players

High definition Blu-ray DVD players

Rev. C

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REVISION HISTORY

3/12—Rev. B to Rev. C

Change to Features Section 1
 Deleted Endnote 1 from Table 1 5
 Added Conditions to Digital Input/Output Specifications—1.8 V Section 8
 Changes to Pin 48 Description, Table 15 22
 Changes to Table 21 35
 Added Register 0x3A to Table 24 38
 Changes to Table 29 42
 Changes to Subaddress 0x87, Bit 7 = 1 Section 49
 Deleted ED/HD Nontandard Timing Mode Section, Figure 59, Figure 60, Figure 61, and Table 42 53
 Added External Sync Polarity Section 54
 Deleted Subcarrier Phase Reset (SCR) Mode and Timing Reset (TR) Mode Sections 54
 Renamed SD Subcarrier Frequency Lock, Subcarrier Phase Reset, and Timing Reset Section to SD Subcarrier Frequency Lock Section 55
 Changes to ED/HD Test Patterns Section 82

9/11—Rev. A to Rev. B

Changes to MPU Port Description Section 28

3/09—Rev. 0 to Rev. A

Changes to Features Section 1
 Deleted Detailed Features Section, Changes to Table 1 4
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 Added Digital Input/Output Specifications—1.8 V Section and Table 7 7
 Changes to Digital Timing Specifications—3.3 V Section and Table 8 8
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 Added Configuration Scripts Section 96

10/06—Revision 0: Initial Version

GENERAL DESCRIPTION

The ADV7340/ADV7341 are high speed, digital-to-analog video encoders in a 64-lead LQFP package. Six high speed, NSV, 3.3 V, 12-bit video DACs provide support for composite (CVBS), S-Video (Y-C), and component (YPrPb/RGB) analog outputs in standard definition (SD), enhanced definition (ED), or high definition (HD) video formats.

The ADV7340/ADV7341 have a 30-bit pixel input port that can be configured in a variety of ways. SD video formats are supported over an SDR interface, and ED/HD video formats are supported over SDR and DDR interfaces. Pixel data can be supplied in either the YCrCb or RGB color space.

The parts also support embedded EAV/SAV timing codes, external video synchronization signals, and I²C[®] communication protocol.

In addition, simultaneous SD and ED/HD input and output are supported. Full-drive DACs ensure that external output buffering is not required, while 216 MHz (SD and ED) and 297 MHz (HD) oversampling ensures that external output filtering is not required.

Cable detection and DAC autopower-down features keep power consumption to a minimum.

Table 1 lists the video standards directly supported by the ADV7340/ADV7341.

Table 1. Standards Directly Supported by the ADV7340/ADV7341

Active Resolution	I/P ¹	Frame Rate (Hz)	Clock Input (MHz)	Standard
720 × 240	P	59.94	27	
720 × 288	P	50	27	
720 × 480	I	29.97	27	ITU-R BT.601/656
720 × 576	I	25	27	ITU-R BT.601/656
640 × 480	I	29.97	24.54	NTSC Square Pixel
768 × 576	I	25	29.5	PAL Square Pixel
720 × 483	P	59.94	27	SMPTE 293M
720 × 483	P	59.94	27	BTA T-1004
720 × 483	P	59.94	27	ITU-R BT.1358
720 × 576	P	50	27	ITU-R BT.1358
720 × 483	P	59.94	27	ITU-R BT.1362
720 × 576	P	50	27	ITU-R BT.1362
1920 × 1035	I	30	74.25	SMPTE 240M
1920 × 1035	I	29.97	74.1758	SMPTE 240M
1280 × 720	P	60, 50, 30, 25, 24	74.25	SMPTE 296M
1280 × 720	P	23.97, 59.94, 29.97	74.1758	SMPTE 296M
1920 × 1080	I	30, 25	74.25	SMPTE 274M
1920 × 1080	I	29.97	74.1758	SMPTE 274M
1920 × 1080	P	30, 25, 24	74.25	SMPTE 274M
1920 × 1080	P	23.98, 29.97	74.1758	SMPTE 274M
1920 × 1080	P	24	74.25	ITU-R BT.709-5

¹ I = interlaced, P = progressive.

FUNCTIONAL BLOCK DIAGRAM

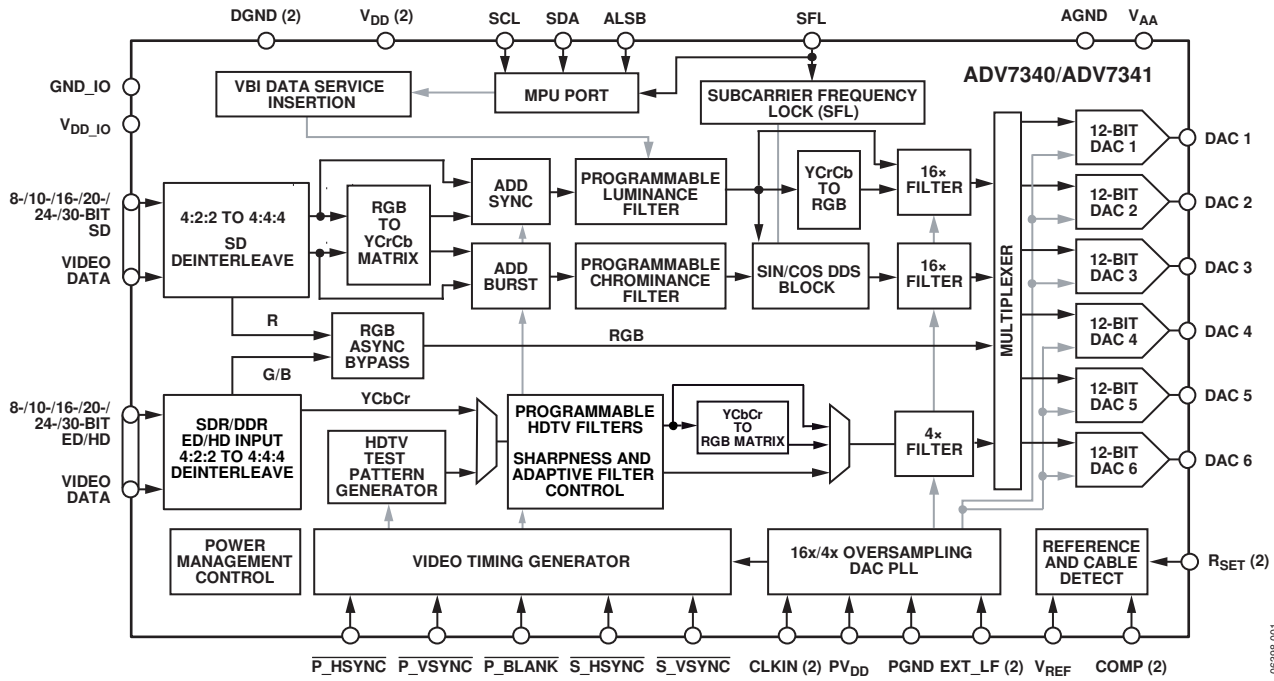


Figure 1.

SPECIFICATIONS

POWER SUPPLY AND VOLTAGE SPECIFICATIONS

All specifications T_{MIN} to T_{MAX} (-40°C to $+85^{\circ}\text{C}$), unless otherwise noted.

Table 2.

Parameter	Min	Typ	Max	Unit
SUPPLY VOLTAGES				
V_{DD}	1.71	1.8	1.89	V
V_{DD_IO}	1.71	3.3	3.63	V
PV_{DD}	1.71	1.8	1.89	V
V_{AA}	2.6	3.3	3.465	V
POWER SUPPLY REJECTION RATIO		0.002		%/%

VOLTAGE REFERENCE SPECIFICATIONS

All specifications T_{MIN} to T_{MAX} (-40°C to $+85^{\circ}\text{C}$), unless otherwise noted.

Table 3.

Parameter	Min	Typ	Max	Unit
Internal Reference Range, V_{REF}	1.186	1.248	1.31	V
External Reference Range, V_{REF}	1.15	1.235	1.31	V
External V_{REF} Current ¹		± 10		μA

¹ External current required to overdrive internal V_{REF} .

INPUT CLOCK SPECIFICATIONS

$V_{DD} = 1.71\text{ V}$ to 1.89 V . $PV_{DD} = 1.71\text{ V}$ to 1.89 V . $V_{AA} = 2.6\text{ V}$ to 3.465 V . $V_{DD_IO} = 1.71\text{ V}$ to 3.63 V .

All specifications T_{MIN} to T_{MAX} (-40°C to $+85^{\circ}\text{C}$), unless otherwise noted.

Table 4.

Parameter	Conditions ¹	Min	Typ	Max	Unit
f_{CLKIN_A}	SD/ED		27		MHz
f_{CLKIN_A}	ED (at 54 MHz)		54		MHz
f_{CLKIN_A}	HD		74.25		MHz
f_{CLKIN_B}	ED		27		MHz
f_{CLKIN_B}	HD		74.25		MHz
CLKIN_A High Time, t_9		40			% of one clock cycle
CLKIN_A Low Time, t_{10}		40			% of one clock cycle
CLKIN_B High Time, t_9		40			% of one clock cycle
CLKIN_B Low Time, t_{10}		40			% of one clock cycle
CLKIN_A Peak-to-Peak Jitter Tolerance			2		$\pm\text{ns}$
CLKIN_B Peak-to-Peak Jitter Tolerance			2		$\pm\text{ns}$

¹ SD = standard definition, ED = enhanced definition (525p/625p), HD = high definition.

ANALOG OUTPUT SPECIFICATIONS

$V_{DD} = 1.71\text{ V to }1.89\text{ V}$. $PV_{DD} = 1.71\text{ V to }1.89\text{ V}$. $V_{AA} = 2.6\text{ V to }3.465\text{ V}$. $V_{DD_IO} = 1.71\text{ V to }3.63\text{ V}$. $V_{REF} = 1.235\text{ V}$ (driven externally). All specifications T_{MIN} to T_{MAX} ($-40^{\circ}\text{C to }+85^{\circ}\text{C}$), unless otherwise noted.

Table 5.

Parameter	Conditions	Min	Typ	Max	Unit
Full-Drive Output Current (Full-Scale)	$R_{SET} = 510\ \Omega$, $R_L = 37.5\ \Omega$ DAC 1, DAC 2, DAC 3 enabled ¹	33	34.6	37	mA
	$R_{SET} = 510\ \Omega$, $R_L = 37.5\ \Omega$ DAC 1 enabled only ²	33	33.5	37	mA
Low-Drive Output Current (Full-Scale) ³	$R_{SET} = 4.12\ \text{k}\Omega$, $R_L = 300\ \Omega$	4.1	4.3	4.5	mA
DAC-to-DAC Matching	DAC 1 to DAC 6		1.0		%
Output Compliance, V_{OC}		0		1.4	V
Output Capacitance, C_{OUT}	DAC 1, DAC 2, DAC 3		10		pF
	DAC 4, DAC 5, DAC 6		6		pF
Analog Output Delay ⁴	DAC 1, DAC 2, DAC 3		8		ns
	DAC 4, DAC 5, DAC 6		6		ns
DAC Analog Output Skew	DAC 1, DAC 2, DAC 3		2		ns
	DAC 4, DAC 5, DAC 6		1		ns

¹ Applicable to full-drive capable DACs only, that is, DAC 1, DAC 2, DAC 3.

² The recommended method of bringing this typical value back to the ideal value is by adjusting Register 0x0B to the recommended value of 0x12.

³ Applicable to all DACs.

⁴ Output delay measured from the 50% point of the rising edge of the input clock to the 50% point of the DAC output full-scale transition.

DIGITAL INPUT/OUTPUT SPECIFICATIONS—3.3 V

$V_{DD} = 1.71\text{ V to }1.89\text{ V}$. $PV_{DD} = 1.71\text{ V to }1.89\text{ V}$. $V_{AA} = 2.6\text{ V to }3.465\text{ V}$. $V_{DD_IO} = 2.97\text{ V to }3.63\text{ V}$. All specifications T_{MIN} to T_{MAX} ($-40^{\circ}\text{C to }+85^{\circ}\text{C}$), unless otherwise noted.

Table 6.

Parameter	Conditions	Min	Typ	Max	Unit
Input High Voltage, V_{IH}		2.0			V
Input Low Voltage, V_{IL}				0.8	V
Input Leakage Current, I_{IN}	$V_{IN} = V_{DD_IO}$			± 10	μA
Input Capacitance, C_{IN}			4		pF
Output High Voltage, V_{OH}	$I_{SOURCE} = 400\ \mu\text{A}$	2.4			V
Output Low Voltage, V_{OL}	$I_{SINK} = 3.2\ \text{mA}$			0.4	V
Three-State Leakage Current	$V_{IN} = 0.4\ \text{V}, 2.4\ \text{V}$			± 1.0	μA
Three-State Output Capacitance			4		pF

DIGITAL INPUT/OUTPUT SPECIFICATIONS—1.8 V

When V_{DD_IO} is set to 1.8 V, all the digital video inputs and control inputs, such as I²C, HS, VS, should use 1.8 V levels.

$V_{DD} = 1.71\text{ V to }1.89\text{ V}$. $PV_{DD} = 1.71\text{ V to }1.89\text{ V}$. $V_{AA} = 2.6\text{ V to }3.465\text{ V}$. $V_{DD_IO} = 1.71\text{ V to }1.89\text{ V}$.

All specifications T_{MIN} to T_{MAX} ($-40^{\circ}\text{C to }+85^{\circ}\text{C}$), unless otherwise noted.

Table 7.

Parameter	Conditions	Min	Typ	Max	Unit
Input High Voltage, V_{IH}		$0.7 V_{DD_IO}$			V
Input Low Voltage, V_{IL}				$0.3 V_{DD_IO}$	V
Input Capacitance, C_{IN}			4		pF
Output High Voltage, V_{OH}	$I_{SOURCE} = 400\ \mu\text{A}$	$V_{DD_IO} - 0.4$			V
Output Low Voltage, V_{OL}	$I_{SINK} = 3.2\ \text{mA}$			0.4	V
Three-State Output Capacitance			4		pF

DIGITAL TIMING SPECIFICATIONS—3.3 V

$V_{DD} = 1.71 \text{ V to } 1.89 \text{ V}$. $PV_{DD} = 1.71 \text{ V to } 1.89 \text{ V}$. $V_{AA} = 2.6 \text{ V to } 3.465 \text{ V}$. $V_{DD_{IO}} = 2.97 \text{ V to } 3.63 \text{ V}$.
All specifications T_{MIN} to T_{MAX} (-40°C to $+85^{\circ}\text{C}$), unless otherwise noted.

Table 8.

Parameter	Conditions ¹	Min	Typ	Max	Unit
VIDEO DATA AND VIDEO CONTROL PORT ^{2, 3}					
Data Input Setup Time, t_{11}^4	SD	2.1			ns
	ED/HD-SDR	2.3			ns
	ED/HD-DDR	2.3			ns
	ED (at 54 MHz)	1.7			ns
Data Input Hold Time, t_{12}^4	SD	1.0			ns
	ED/HD-SDR	1.1			ns
	ED/HD-DDR	1.1			ns
	ED (at 54 MHz)	1.0			ns
Control Input Setup Time, t_{11}^4	SD	2.1			ns
	ED/HD-SDR or ED/HD-DDR	2.3			ns
	ED (at 54 MHz)	1.7			ns
Control Input Hold Time, t_{12}^4	SD	1.0			ns
	ED/HD-SDR or ED/HD-DDR	1.1			ns
	ED (at 54 MHz)	1.0			ns
Control Output Access Time, t_{13}^4	SD			12	ns
	ED/HD-SDR, ED/HD-DDR or ED (at 54 MHz)			10	ns
Control Output Hold Time, t_{14}^4	SD	4.0			ns
	ED/HD-SDR, ED/HD-DDR or ED (at 54 MHz)	3.5			ns
PIPELINE DELAY ⁵					
SD ¹					
CVBS/YC Outputs (2×)	SD oversampling disabled		68		Clock cycles
CVBS/YC Outputs (16×)	SD oversampling enabled		67		Clock cycles
Component Outputs (2×)	SD oversampling disabled		78		Clock cycles
Component Outputs (16×)	SD oversampling enabled		84		Clock cycles
ED ¹					
Component Outputs (1×)	ED oversampling disabled		41		Clock cycles
Component Outputs (8×)	ED oversampling enabled		46		Clock cycles
HD ¹					
Component Outputs (1×)	HD oversampling disabled		40		Clock cycles
Component Outputs (4×)	HD oversampling enabled		44		Clock cycles

¹ SD = standard definition, ED = enhanced definition (525p/625p), HD = high definition, SDR = single data rate, DDR = dual data rate.

² Video data: C[9:0], Y[9:0], and S[9:0].

³ Video control: P_HSYNC, P_VSYNC, P_BLANK, S_HSYNC, and S_VSYNC.

⁴ Guaranteed by characterization.

⁵ Guaranteed by design.

DIGITAL TIMING SPECIFICATIONS—1.8 V

$V_{DD} = 1.71 \text{ V to } 1.89 \text{ V}$. $PV_{DD} = 1.71 \text{ V to } 1.89 \text{ V}$. $V_{AA} = 2.6 \text{ V to } 3.465 \text{ V}$. $V_{DD,IO} = 1.71 \text{ V to } 1.89 \text{ V}$.

All specifications T_{MIN} to T_{MAX} (-40°C to $+85^{\circ}\text{C}$), unless otherwise noted.

Table 9.

Parameter	Conditions ¹	Min	Typ	Max	Unit
VIDEO DATA AND VIDEO CONTROL PORT ^{2, 3}					
Data Input Setup Time, t_{11}^4	SD	1.4			ns
	ED/HD-SDR	1.9			ns
	ED/HD-DDR	1.9			ns
	ED (at 54 MHz)	1.6			ns
Data Input Hold Time, t_{12}^4	SD	1.4			ns
	ED/HD-SDR	1.5			ns
	ED/HD-DDR	1.5			ns
	ED (at 54 MHz)	1.3			ns
Control Input Setup Time, t_{11}^4	SD	1.4			ns
	ED/HD-SDR or ED/HD-DDR	1.2			ns
	ED (at 54 MHz)	1.0			ns
Control Input Hold Time, t_{12}^4	SD	1.4			ns
	ED/HD-SDR or ED/HD-DDR	1.0			ns
	ED (at 54 MHz)	1.0			ns
Control Output Access Time, t_{13}^4	SD			13	ns
	ED/HD-SDR, ED/HD-DDR or ED (at 54 MHz)			12	ns
Control Output Hold Time, t_{14}^4	SD	4.0			ns
	ED/HD-SDR, ED/HD-DDR or ED (at 54 MHz)	5.0			ns
PIPELINE DELAY ⁵					
SD ¹					
CVBS/YC Outputs (2×)	SD oversampling disabled		68		Clock cycles
CVBS/YC Outputs (16×)	SD oversampling enabled		67		Clock cycles
Component Outputs (2×)	SD oversampling disabled		78		Clock cycles
Component Outputs (16×)	SD oversampling enabled		84		Clock cycles
ED ¹					
Component Outputs (1×)	ED oversampling disabled		41		Clock cycles
Component Outputs (8×)	ED oversampling enabled		46		Clock cycles
HD ¹					
Component Outputs (1×)	HD oversampling disabled		40		Clock cycles
Component Outputs (4×)	HD oversampling enabled		44		Clock cycles

¹ SD = standard definition, ED = enhanced definition (525p/625p), HD = high definition, SDR = single data rate, DDR = dual data rate.

² Video data: C[9:0], Y[9:0], and S[9:0].

³ Video control: P_HSYNC, P_VSYNC, P_BLANK, S_HSYNC, and S_VSYNC.

⁴ Guaranteed by characterization.

⁵ Guaranteed by design.

MPU PORT TIMING SPECIFICATIONS

$V_{DD} = 1.71\text{ V to }1.89\text{ V}$. $PV_{DD} = 1.71\text{ V to }1.89\text{ V}$. $V_{AA} = 2.6\text{ V to }3.465\text{ V}$. $V_{DD_IO} = 1.71\text{ V to }3.63\text{ V}$.
All specifications T_{MIN} to T_{MAX} (-40°C to $+85^{\circ}\text{C}$), unless otherwise noted.

Table 10.

Parameter	Conditions	Min	Typ	Max	Unit
MPU PORT, I ² C MODE ¹	See Figure 19				
SCL Frequency		0		400	kHz
SCL High Pulse Width, t_1		0.6			μs
SCL Low Pulse Width, t_2		1.3			μs
Hold Time (Start Condition), t_3		0.6			μs
Setup Time (Start Condition), t_4		0.6			μs
Data Setup Time, t_5		100			ns
SDA, SCL Rise Time, t_6				300	ns
SDA, SCL Fall Time, t_7				300	ns
Setup Time (Stop Condition), t_8		0.6			μs

¹ Guaranteed by characterization.

POWER SPECIFICATIONS

$V_{DD} = 1.8\text{ V}$, $PV_{DD} = 1.8\text{ V}$, $V_{AA} = 3.3\text{ V}$, $V_{DD_IO} = 3.3\text{ V}$, $T_A = 25^{\circ}\text{C}$.

Table 11.

Parameter	Conditions	Min	Typ	Max	Unit
NORMAL POWER MODE ^{1, 2}					
I_{DD} ³	SD only (16 \times oversampling)		90		mA
	ED only (8 \times oversampling) ⁴		65		mA
	HD only (4 \times oversampling) ⁴		91		mA
	SD (16 \times oversampling) and ED (8 \times oversampling)		95		mA
	SD (16 \times oversampling) and HD (4 \times oversampling)		122		mA
I_{DD_IO}			1		mA
I_{AA} ⁵	Three DACs enabled (ED/HD only)		124		mA
	Six DACs enabled (SD only and simultaneous modes)		140		mA
I_{PLL}	SD only, ED only, or HD only modes		5		mA
	Simultaneous modes		10		mA
SLEEP MODE					
I_{DD}			5		μA
I_{AA}			0.3		μA
I_{DD_IO}			0.2		μA
I_{PLL}			0.1		μA

¹ $R_{SET1} = 510\ \Omega$ (DAC 1, DAC 2, and DAC 3 operating in full-drive mode). $R_{SET2} = 4.12\ \text{k}\Omega$ (DAC 4, DAC 5, and DAC 6 operating in low-drive mode).

² 75% color bar test pattern applied to pixel data pins.

³ I_{DD} is the continuous current required to drive the digital core.

⁴ Applicable to both single data rate (SDR) and dual data rate (DDR) input modes.

⁵ I_{AA} is the total current required to supply all DACs.

VIDEO PERFORMANCE SPECIFICATIONS

$V_{DD} = 1.8\text{ V}$, $PV_{DD} = 1.8\text{ V}$, $V_{AA} = 3.3\text{ V}$, $V_{DD_{IO}} = 3.3\text{ V}$, $T_A = 25^\circ\text{C}$, V_{REF} driven externally.

Table 12.

Parameter	Conditions	Min	Typ	Max	Unit
STATIC PERFORMANCE					
Resolution			12		Bits
Integral Nonlinearity	$R_{SET1} = 510\ \Omega$, $R_{L1} = 37.5\ \Omega$		0.75		LSBs
	$R_{SET2} = 4.12\ \text{k}\Omega$, $R_{L2} = 300\ \Omega$		1		LSBs
Differential Nonlinearity ¹ +ve	$R_{SET1} = 510\ \Omega$, $R_{L1} = 37.5\ \Omega$		0.25		LSBs
	$R_{SET2} = 4.12\ \text{k}\Omega$, $R_{L2} = 300\ \Omega$		0.8		LSBs
Differential Nonlinearity ¹ -ve	$R_{SET1} = 510\ \Omega$, $R_{L1} = 37.5\ \Omega$		0.43		LSBs
	$R_{SET2} = 4.12\ \text{k}\Omega$, $R_{L2} = 300\ \Omega$		0.35		LSBs
STANDARD DEFINITION (SD) MODE					
Luminance Nonlinearity			0.35		±%
Differential Gain	NTSC		0.3		%
Differential Phase	NTSC		0.4		Degrees
SNR	Luma ramp		63		dB
SNR	Flat field full bandwidth		79.5		dB
ENHANCED DEFINITION (ED) MODE					
Luma Bandwidth			12.5		MHz
Chroma Bandwidth			5.8		MHz
HIGH DEFINITION (HD) MODE					
Luma Bandwidth			30		MHz
Chroma Bandwidth			13.75		MHz

¹ Differential nonlinearity (DNL) measures the deviation of the actual DAC output voltage step from the ideal. For +ve DNL, the actual step value lies above the ideal step value. For -ve DNL, the actual step value lies below the ideal step value.

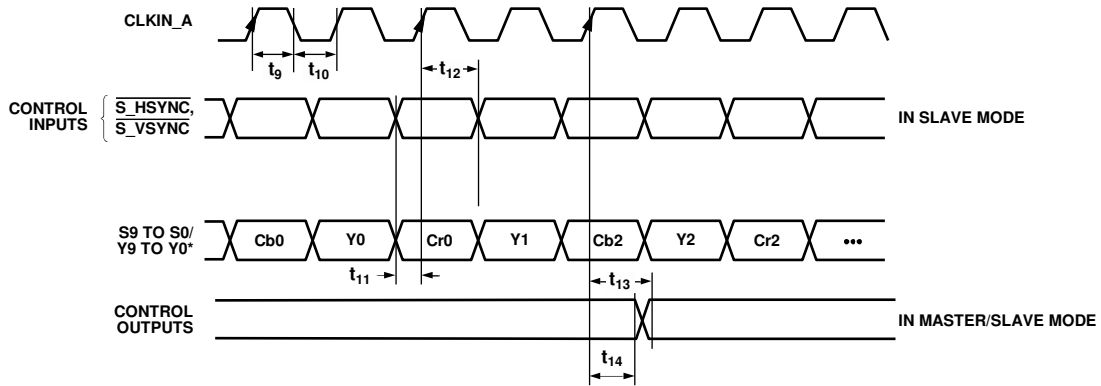
TIMING DIAGRAMS

The following abbreviations are used in Figure 2 to Figure 13:

- t_9 = clock high time
- t_{10} = clock low time
- t_{11} = data setup time
- t_{12} = data hold time

- t_{13} = control output access time
- t_{14} = control output hold time

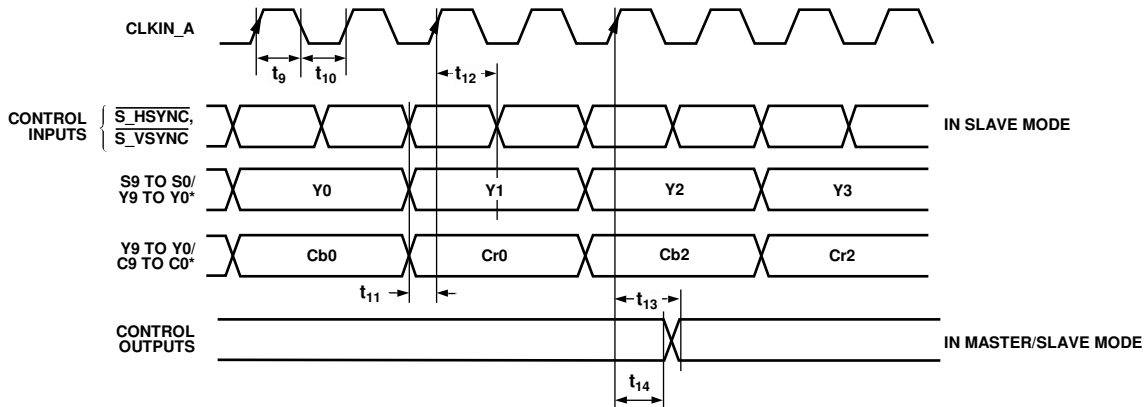
In addition, refer to Table 36 for the ADV7340/ADV7341 input configuration.



*SELECTED BY SUBADDRESS 0x01, BIT 7.

Figure 2. SD Only, 8-/10-Bit, 4:2:2 YCrCb Pixel Input Mode (Input Mode 000)

06398-002



*SELECTED BY SUBADDRESS 0x01, BIT 7.

Figure 3. SD Only, 16-/20-Bit, 4:2:2 YCrCb Pixel Input Mode (Input Mode 000)

06398-003

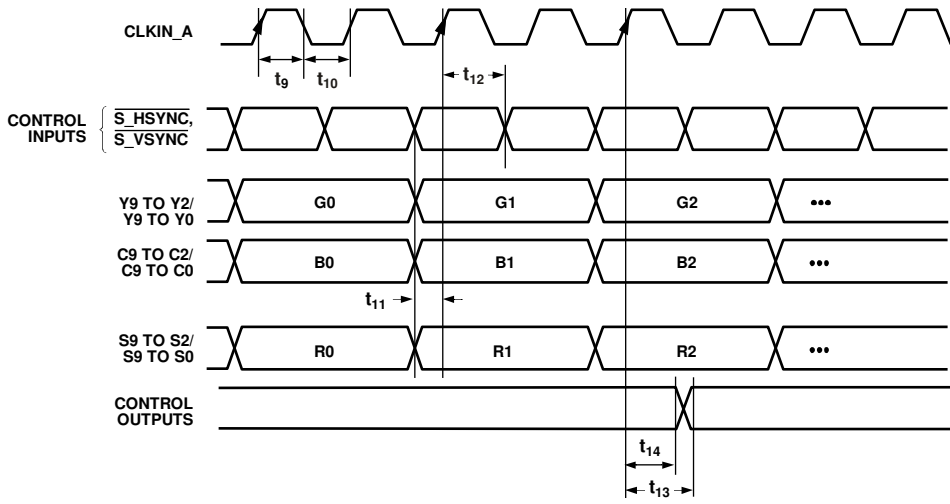


Figure 4. SD Only, 24-/30-Bit, 4:4:4 RGB Pixel Input Mode (Input Mode 000)

063398-004

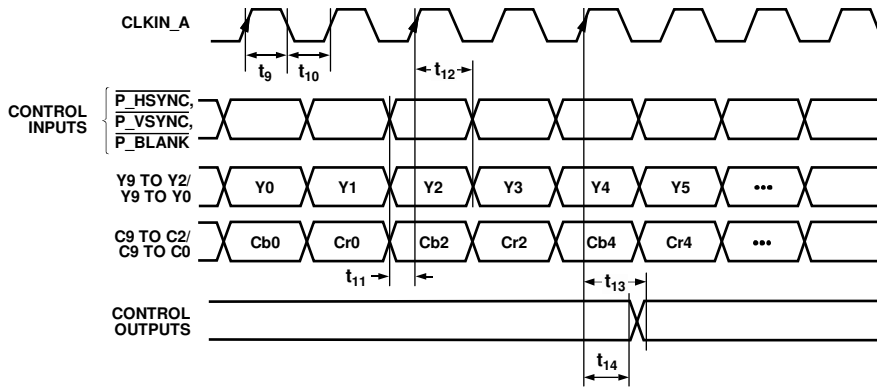


Figure 5. ED/HD-SDR Only, 16-/20-Bit, 4:2:2 YCrCb Pixel Input Mode (Input Mode 001)

063398-005

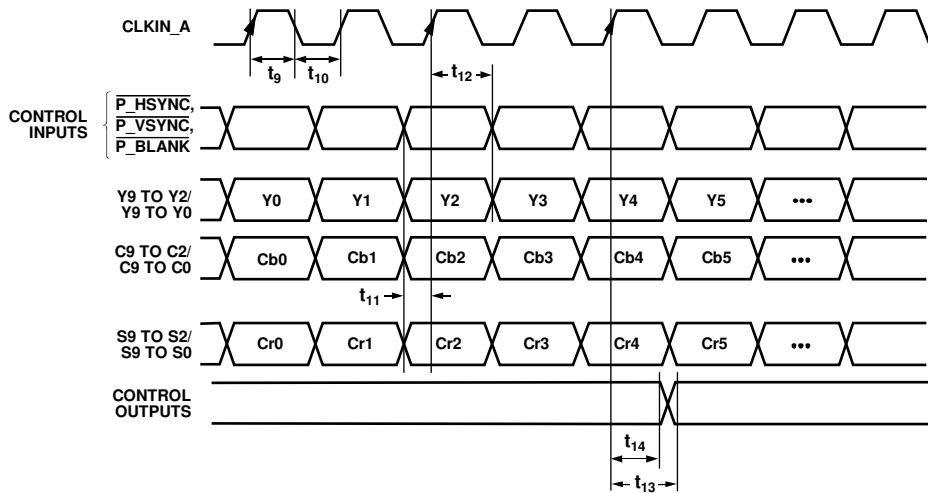


Figure 6. ED/HD-SDR Only, 24-/30-Bit, 4:4:4 YCrCb Pixel Input Mode (Input Mode 001)

063398-006

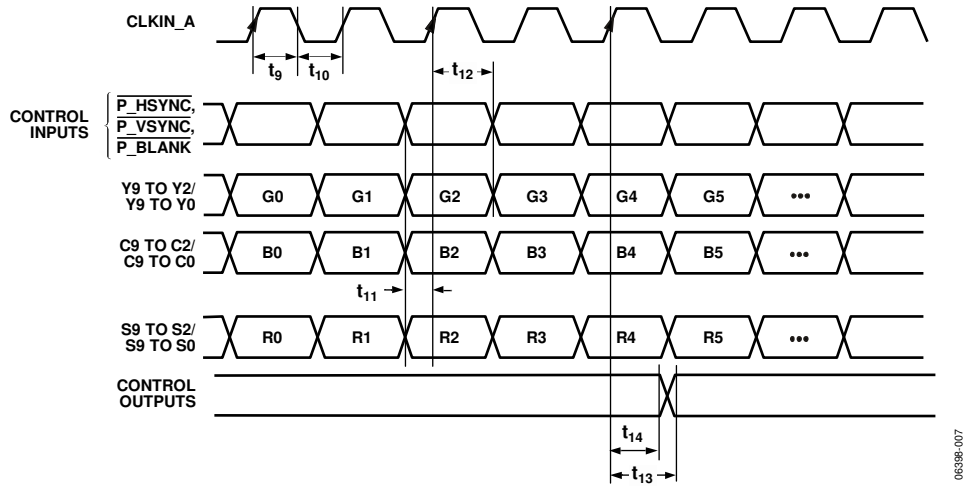
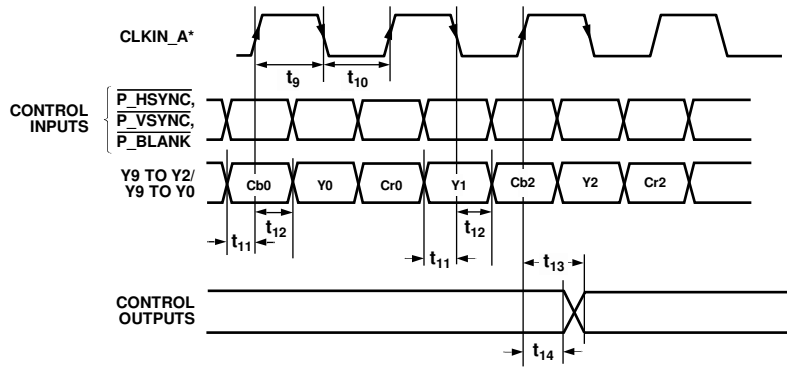


Figure 7. ED/HDMI-SDR Only, 24-/30-Bit, 4:4:4 RGB Pixel Input Mode (Input Mode 001)

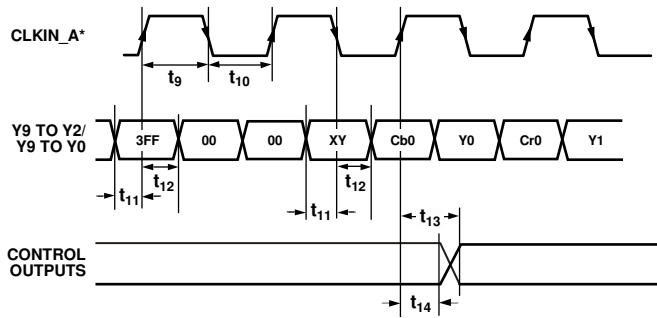
06398-007



*LUMA/CHROMA CLOCK RELATIONSHIP CAN BE INVERTED USING SUBADDRESS 0x01, BITS 1 AND 2.

Figure 8. ED/HDMI-DDR Only, 8-/10-Bit, 4:2:2 YCrCb (HSYNC/VSYNC) Pixel Input Mode (Input Mode 010)

06398-008



*LUMA/CHROMA CLOCK RELATIONSHIP CAN BE INVERTED USING SUBADDRESS 0x01, BITS 1 AND 2.

Figure 9. ED/HDMI-DDR Only, 8-/10-Bit, 4:2:2 YCrCb (EAV/SAV) Pixel Input Mode (Input Mode 010)

06398-009

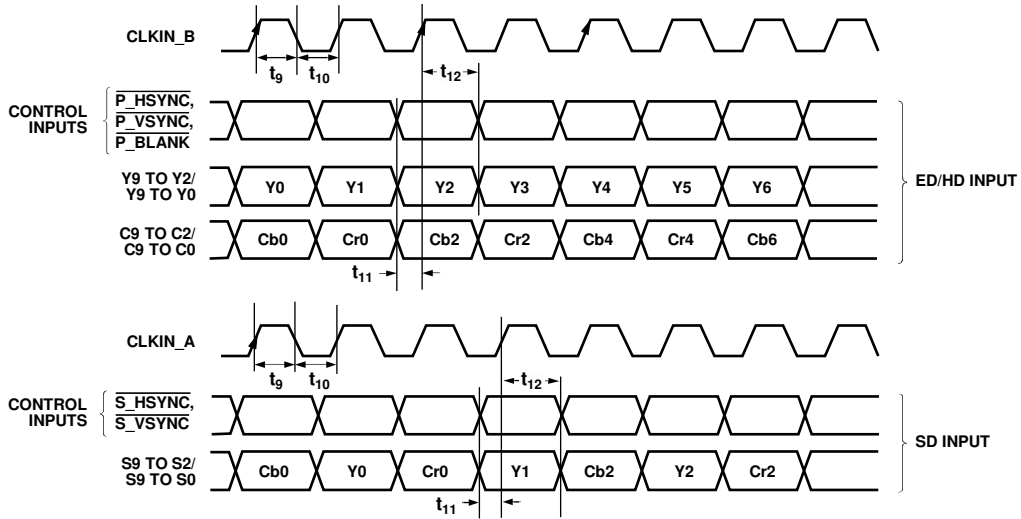


Figure 10. SD, ED/HD-SDR Input Mode, 16-/20-Bit, 4:2:2 ED/HD and 8-/10-Bit, SD Pixel Input Mode (Input Mode 011)

06398-010

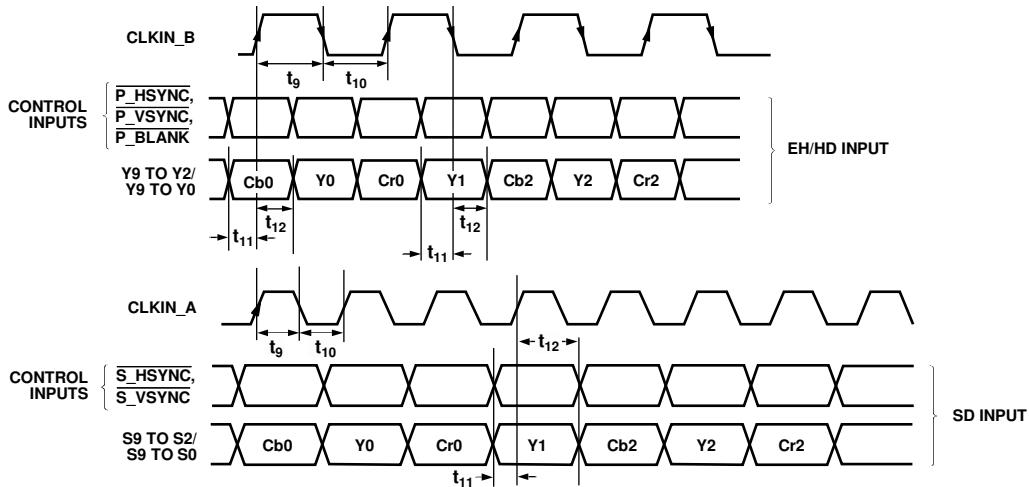


Figure 11. SD, ED/HD-DDR Input Mode, 8-/10-Bit, 4:2:2 ED/HD and 8-/10-Bit, SD Pixel Input Mode (Input Mode 100)

06398-011

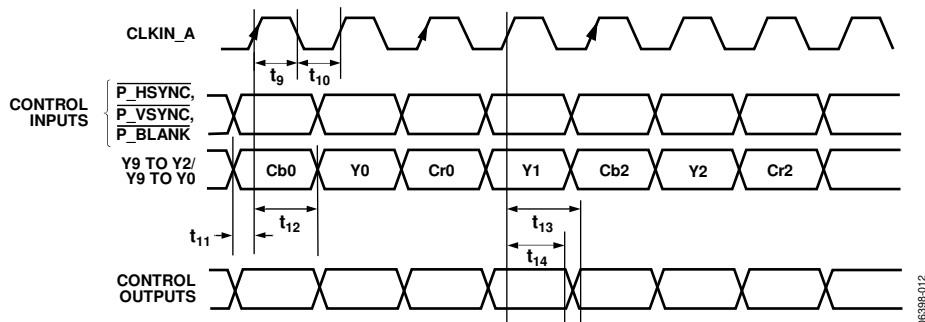


Figure 12. ED Only (at 54 MHz), 8-/10-Bit, 4:2:2 YCrCb (HSYNC/VSYNC) Pixel Input Mode (Input Mode 111)

06398-012

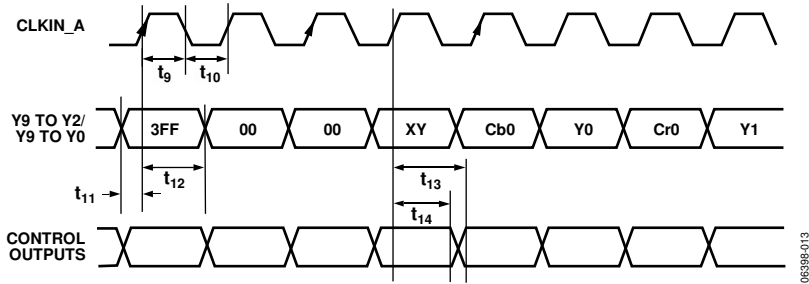
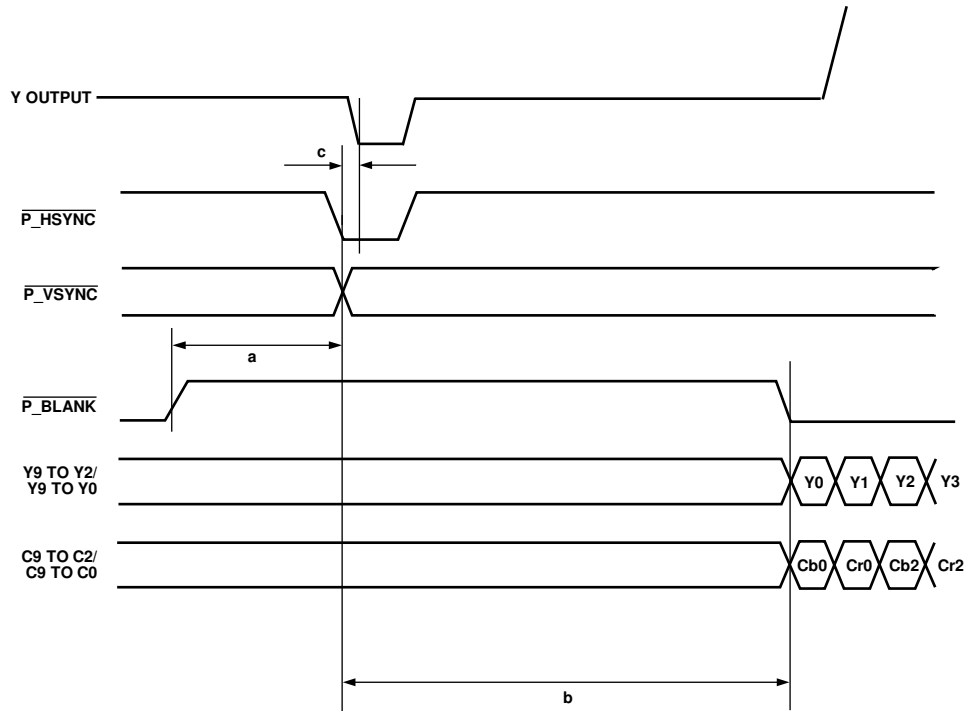


Figure 13. ED Only (at 54 MHz), 8-/10-Bit, 4:2:2 YCrCb (EAV/SAV) Pixel Input Mode (Input Mode 111)

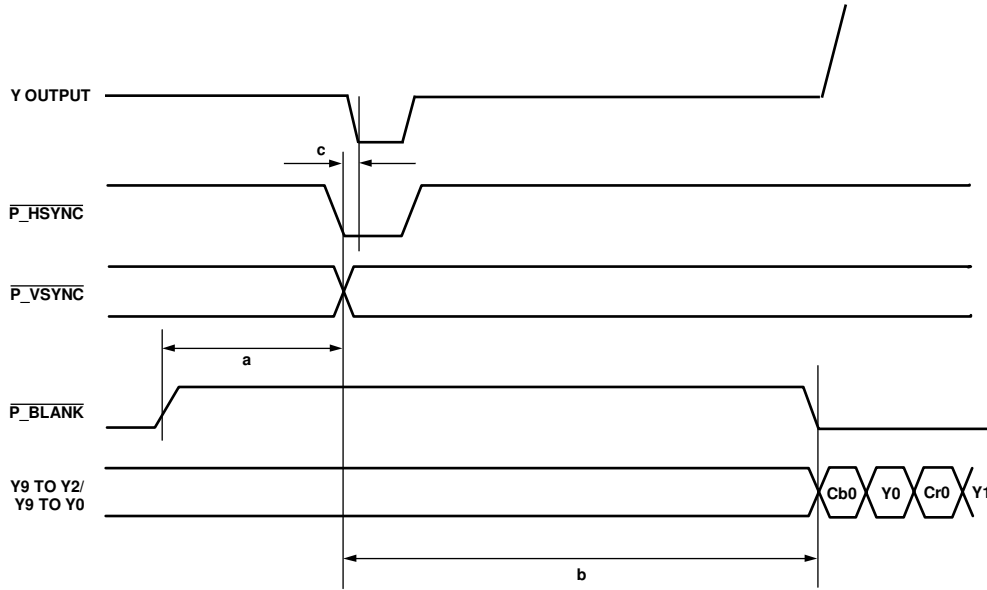


a AND b AS PER RELEVANT STANDARD.

c = PIPELINE DELAY. PLEASE REFER TO RELEVANT PIPELINE DELAY. THIS CAN BE FOUND IN THE DIGITAL TIMING SPECIFICATION SECTION OF THE DATA SHEET.

A FALLING EDGE OF $\overline{\text{HSYNC}}$ INTO THE ENCODER GENERATES A SYNC FALLING EDGE ON THE OUTPUT AFTER A TIME EQUAL TO THE PIPELINE DELAY.

Figure 14. ED-SDR, 16-/20-Bit, 4:2:2 YCrCb ($\overline{\text{HSYNC}}/\overline{\text{VSYNC}}$) Input Timing Diagram



a = 32 CLKCYCLES FOR 525p
 a = 24 CLKCYCLES FOR 625p
 AS RECOMMENDED BY STANDARD

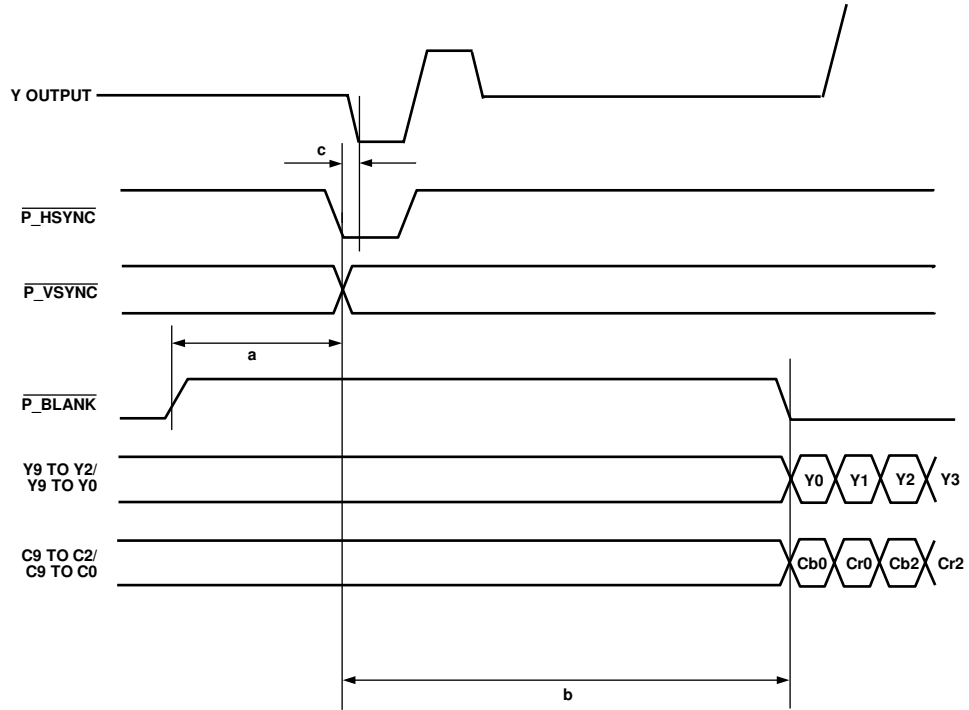
b(MIN) = 244 CLKCYCLES FOR 525p
 b(MIN) = 264 CLKCYCLES FOR 625p

c = PIPELINE DELAY. PLEASE REFER TO RELEVANT PIPELINE DELAY. THIS CAN BE FOUND IN THE DIGITAL TIMING SPECIFICATION SECTION OF THE DATA SHEET.

A FALLING EDGE OF $\overline{\text{HSYNC}}$ INTO THE ENCODER GENERATES A SYNC FALLING EDGE ON THE OUTPUT AFTER A TIME EQUAL TO THE PIPELINE DELAY.

Figure 15. ED-DDR, 8-/10-Bit, 4:2:2 YCrCb ($\overline{\text{HSYNC}}/\overline{\text{VSYNC}}$) Input Timing Diagram

06398-015



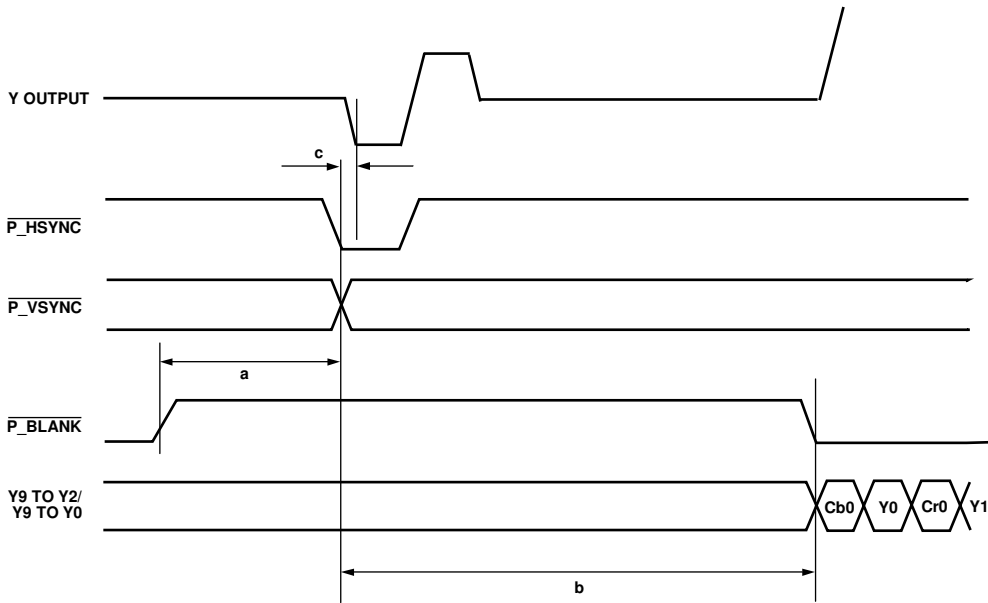
a AND b AS PER RELEVANT STANDARD.

c = PIPELINE DELAY. PLEASE REFER TO RELEVANT PIPELINE DELAY. THIS CAN BE FOUND IN THE DIGITAL TIMING SPECIFICATION SECTION OF THE DATA SHEET.

A FALLING EDGE OF HSYNC INTO THE ENCODER GENERATES A FALLING EDGE OF TRI-LEVEL SYNC ON THE OUTPUT AFTER A TIME EQUAL TO THE PIPELINE DELAY.

06398-016

Figure 16. HD-SDR, 16-/20-Bit, 4:2:2 YCrCb (HSYNC/VSYNC) Input Timing Diagram



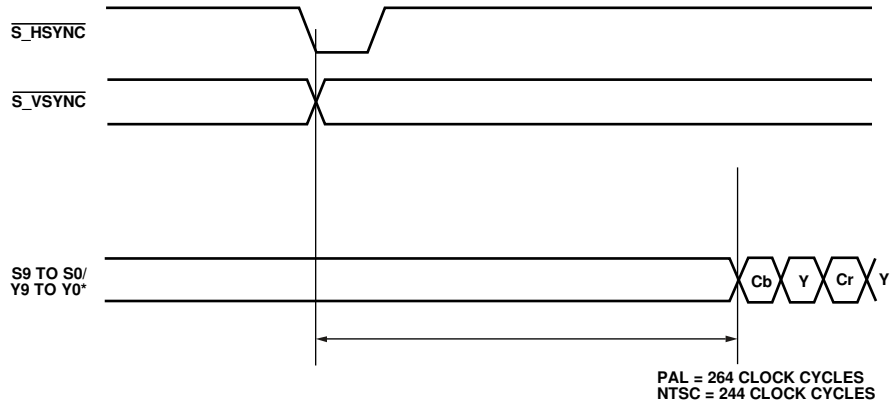
a AND b AS PER RELEVANT STANDARD.

c = PIPELINE DELAY. PLEASE REFER TO RELEVANT PIPELINE DELAY. THIS CAN BE FOUND IN THE DIGITAL TIMING SPECIFICATION SECTION OF THE DATA SHEET.

A FALLING EDGE OF HSYNC INTO THE ENCODER GENERATES A FALLING EDGE OF TRI-LEVEL SYNC ON THE OUTPUT AFTER A TIME EQUAL TO THE PIPELINE DELAY.

06398-017

Figure 17. HD-DDR, 8-/10-Bit, 4:2:2 YCrCb (HSYNC/VSYNC) Input Timing Diagram



*SELECTED BY SUBADDRESS 0x01, BIT 7.

Figure 18. SD Input Timing Diagram (Timing Mode 1)

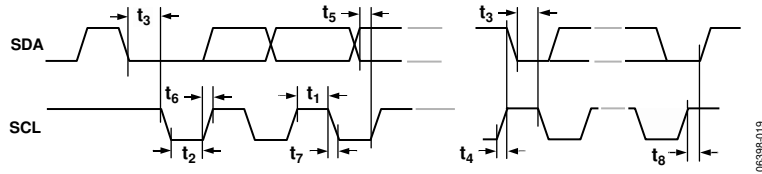


Figure 19. MPU Port Timing Diagram (I²C Mode)

ABSOLUTE MAXIMUM RATINGS

Table 13.

Parameter ¹	Rating
V _{AA} to AGND	−0.3 V to +3.9 V
V _{DD} to DGND	−0.3 V to +2.3 V
PV _{DD} to PGND	−0.3 V to +2.3 V
V _{DD_IO} to GND_IO	−0.3 V to +3.9 V
AGND to DGND	−0.3 V to +0.3 V
AGND to PGND	−0.3 V to +0.3 V
AGND to GND_IO	−0.3 V to +0.3 V
DGND to PGND	−0.3 V to +0.3 V
DGND to GND_IO	−0.3 V to +0.3 V
PGND to GND_IO	−0.3 V to +0.3 V
Digital Input Voltage to GND_IO	−0.3 V to V _{DD_IO} + 0.3 V
Analog Outputs to AGND	−0.3 V to V _{AA}
Maximum CLKIN Input Frequency	80 MHz
Storage Temperature Range (T _s)	−65°C to +150°C
Junction Temperature (T _j)	150°C
Lead Temperature (Soldering, 10 sec)	260°C

¹ Analog output short circuit to any power supply or common can be of an indefinite duration.

Stresses above those listed under Absolute Maximum Ratings may cause permanent damage to the device. This is a stress rating only; functional operation of the device at these or any other conditions above those indicated in the operational section of this specification is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

The ADV7340/ADV7341 are high performance integrated circuits with an ESD rating of <1 kV, and they are ESD sensitive. Proper precautions should be taken for handling and assembly.

THERMAL RESISTANCE

θ_{JA} is specified for the worst-case conditions, that is, a device soldered in a circuit board for surface-mount packages.

Table 14. Thermal Resistance¹

Package Type	θ_{JA}	θ_{JC}	Unit
64-Lead LQFP	47	11	°C/W

¹ Values are based on a JEDEC 4-layer test board.

The ADV7340/ADV7341 are RoHS-compliant, Pb-free products. The lead finish is 100% pure Sn electroplate. The devices are suitable for Pb-free applications up to 255°C (±5°C) IR reflow (JEDEC STD-20).

Each part is backward compatible with conventional SnPb soldering processes. The electroplated Sn coating can be soldered with Sn/Pb solder paste at conventional reflow temperatures of 220°C to 235°C.

ESD CAUTION



ESD (electrostatic discharge) sensitive device. Charged devices and circuit boards can discharge without detection. Although this product features patented or proprietary protection circuitry, damage may occur on devices subjected to high energy ESD. Therefore, proper ESD precautions should be taken to avoid performance degradation or loss of functionality.

PIN CONFIGURATION AND FUNCTION DESCRIPTIONS

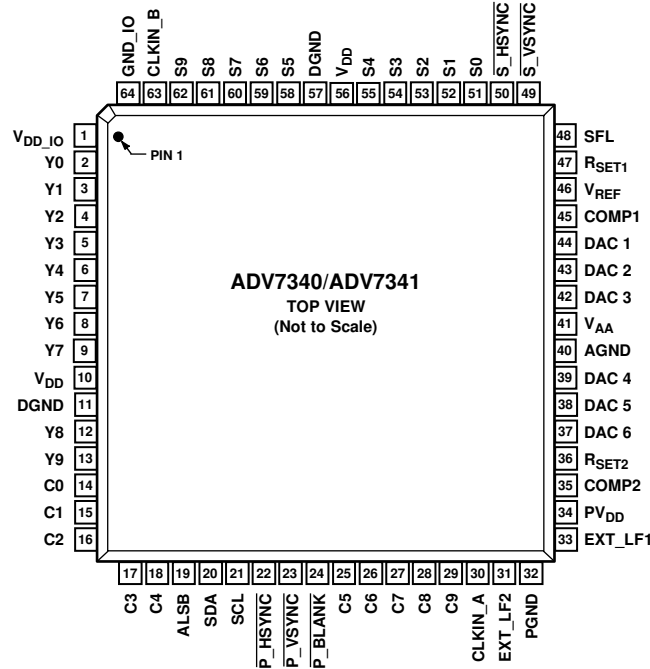


Figure 20. Pin Configuration

Table 15. Pin Function Descriptions

Pin No.	Mnemonic	Input/Output	Description
13, 12, 9 to 2	Y9 to Y0	I	10-Bit Pixel Port (Y9 to Y0). Y0 is the LSB. Refer to Table 36 for input modes.
29 to 25, 18 to 14	C9 to C0	I	10-Bit Pixel Port (C9 to C0). C0 is the LSB. Refer to Table 36 for input modes.
62 to 58, 55 to 51	S9 to S0	I	10-Bit Pixel Port (S9 to S0). S0 is the LSB. Refer to Table 36 for input modes.
30	CLKIN_A	I	Pixel Clock Input for HD Only (74.25 MHz), ED ¹ Only (27 MHz or 54 MHz), or SD Only (27 MHz).
63	CLKIN_B	I	Pixel Clock Input for Dual Modes Only. Requires a 27 MHz reference clock for ED operation or a 74.25 MHz reference clock for HD operation.
50	$\overline{S_HSYNC}$	I/O	SD Horizontal Synchronization Signal. This pin can also be configured to output an SD, ED, or HD horizontal synchronization signal. See the External Horizontal and Vertical Synchronization Control section.
49	$\overline{S_VSYNC}$	I/O	SD Vertical Synchronization Signal. This pin can also be configured to output an SD, ED, or HD vertical synchronization signal. See the External Horizontal and Vertical Synchronization Control section.
22	$\overline{P_HSYNC}$	I	ED/HD Horizontal Synchronization Signal. See the External Horizontal and Vertical Synchronization Control section.
23	$\overline{P_VSYNC}$	I	ED/HD Vertical Synchronization Signal. See the External Horizontal and Vertical Synchronization Control section.
24	$\overline{P_BLANK}$	I	ED/HD Blanking Signal. See the External Horizontal and Vertical Synchronization Control section.
48	SFL	I/O	Subcarrier Frequency Lock (SFL) Input.
47	RSET1	I	This pin is used to control the amplitudes of the DAC 1, DAC 2, and DAC 3 outputs. For full-drive operation (for example, into a 37.5 Ω load), a 510 Ω resistor must be connected from RSET1 to AGND. For low-drive operation (for example, into a 300 Ω load), a 4.12 k Ω resistor must be connected from RSET1 to AGND.
36	RSET2	I	This pin is used to control the amplitudes of the DAC 4, DAC 5, and DAC 6 outputs. A 4.12 k Ω resistor must be connected from RSET2 to AGND.

Pin No.	Mnemonic	Input/ Output	Description
45, 35	COMP1, COMP2	O	Compensation Pins. Connect a 2.2 nF capacitor from both COMP pins to V _{AA} .
44, 43, 42	DAC 1, DAC 2, DAC 3	O	DAC Outputs. Full- and low-drive capable DACs.
39, 38, 37	DAC 4, DAC 5, DAC 6	O	DAC Outputs. Low-drive only capable DACs.
21	SCL	I	I ² C Clock Input.
20	SDA	I/O	I ² C Data Input/Output.
19	ALSB	I	This signal sets up the LSB ² of the MPU I ² C address (see the Power Supply Sequencing section for more information).
46	V _{REF}		Optional External Voltage Reference Input for DACs or Voltage Reference Output.
41	V _{AA}	P	Analog Power Supply (3.3 V).
10, 56	V _{DD}	P	Digital Power Supply (1.8 V). For dual-supply configurations, V _{DD} can be connected to other 1.8 V supplies through a ferrite bead or suitable filtering.
1	V _{DD_IO}	P	Input/Output Digital Power Supply (1.8 V or 3.3 V).
34	PV _{DD}	P	PLL Power Supply (1.8 V). For dual-supply configurations, PV _{DD} can be connected to other 1.8 V supplies through a ferrite bead or suitable filtering.
33	EXT_LF1	I	External Loop Filter for On-Chip PLL 1.
31	EXT_LF2	I	External Loop Filter for On-Chip PLL 2.
32	PGND	G	PLL Ground Pin.
40	AGND	G	Analog Ground Pin.
11, 57	DGND	G	Digital Ground Pin.
64	GND_IO	G	Input/Output Supply Ground Pin.

¹ ED = enhanced definition = 525p and 625p.

² LSB = least significant bit. In the ADV7340, setting the LSB to 0 sets the I²C address to 0xD4. Setting it to 1 sets the I²C address to 0xD6. In the ADV7341, setting the LSB to 0 sets the I²C address to 0x54. Setting it to 1 sets the I²C address to 0x56.

TYPICAL PERFORMANCE CHARACTERISTICS

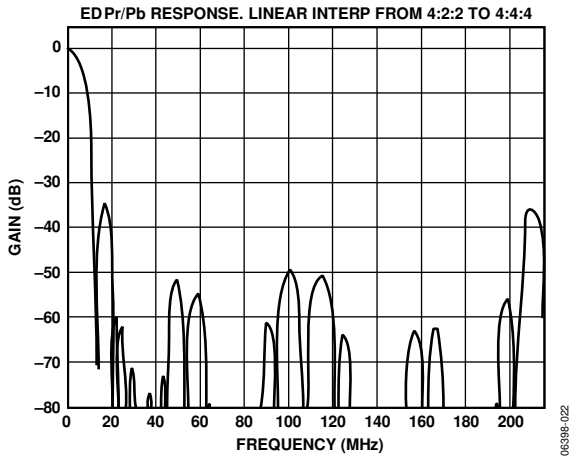


Figure 21. ED 8x Oversampling, PrPb Filter (Linear) Response

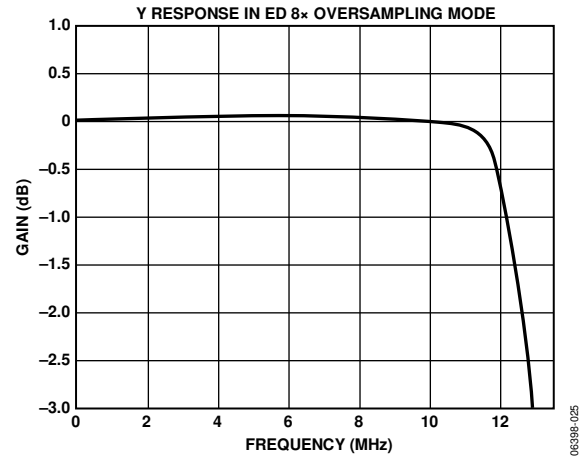


Figure 24. ED 8x Oversampling, Y Filter Response (Focus on Pass Band)

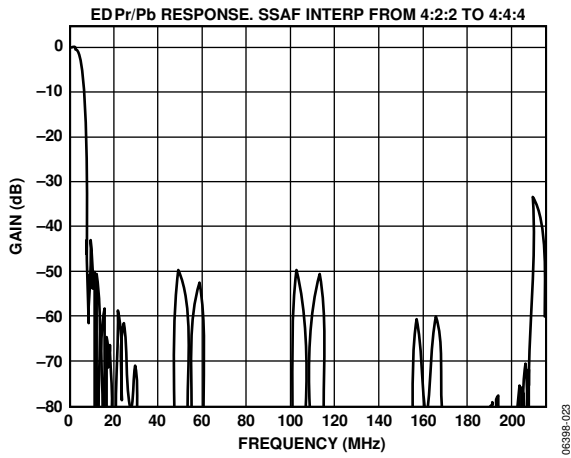


Figure 22. ED 8x Oversampling, PrPb Filter (SSAF™) Response

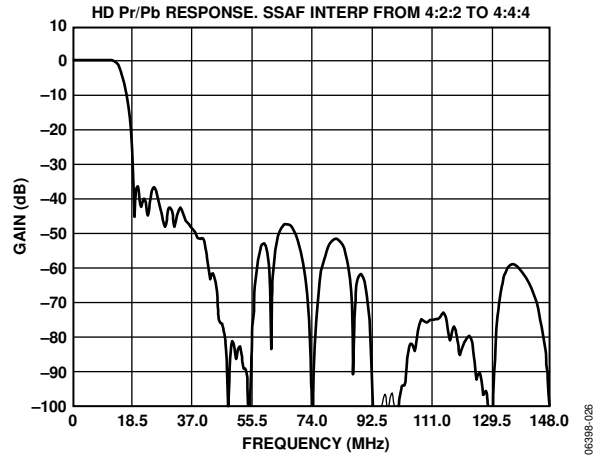


Figure 25. HD 4x Oversampling, PrPb (SSAF) Filter Response (4:2:2 Input)

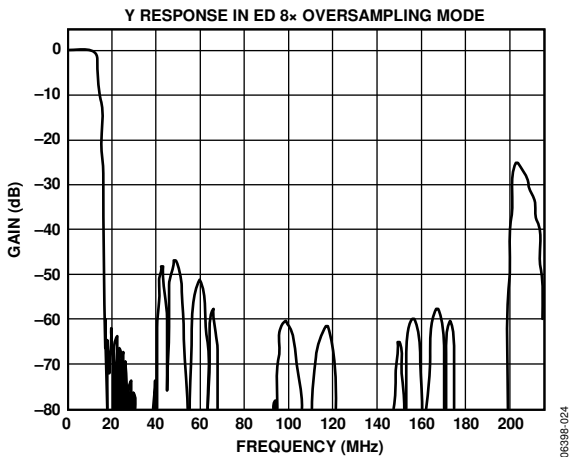


Figure 23. ED 8x Oversampling, Y Filter Response

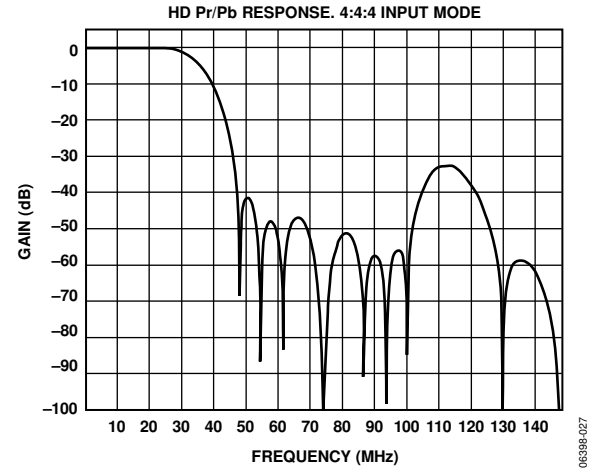


Figure 26. HD 4x Oversampling, PrPb (SSAF) Filter Response (4:4:4 Input)

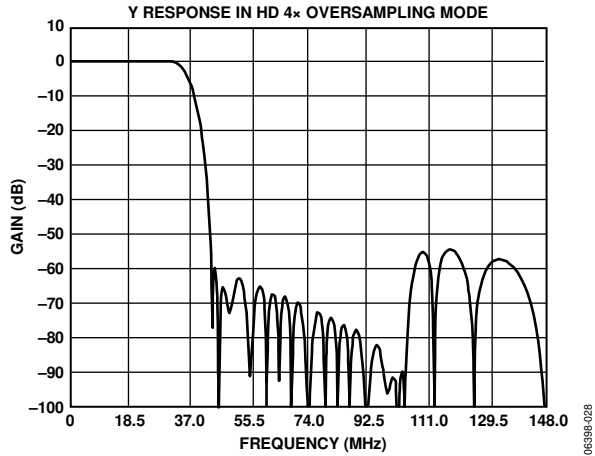


Figure 27. HD 4x Oversampling, Y Filter Response

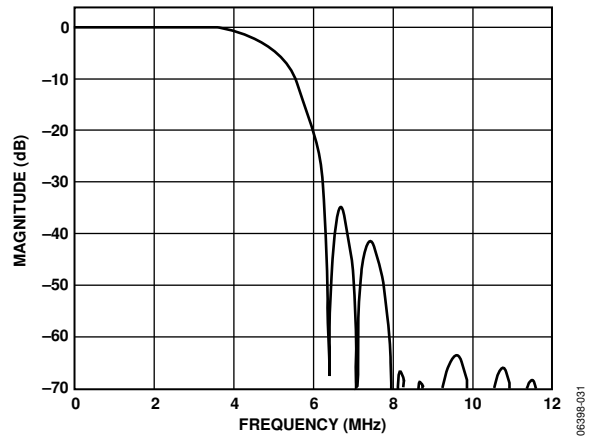


Figure 30. SD PAL, Luma Low-Pass Filter Response

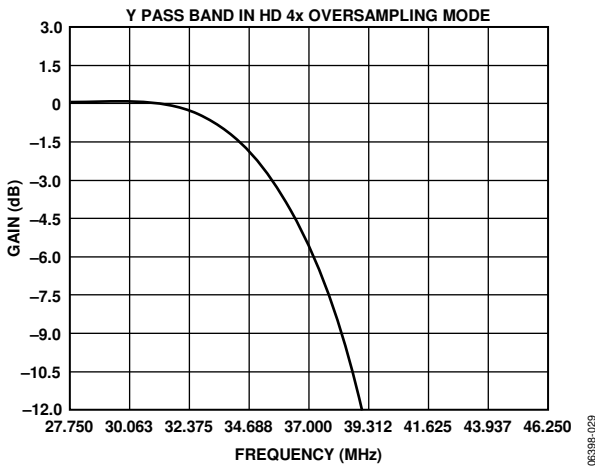


Figure 28. HD 4x Oversampling, Y Filter Response (Focus on Pass Band)

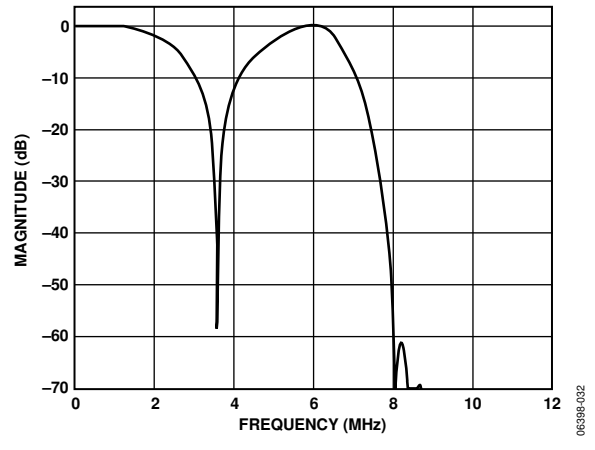


Figure 31. SD NTSC, Luma Notch Filter Response

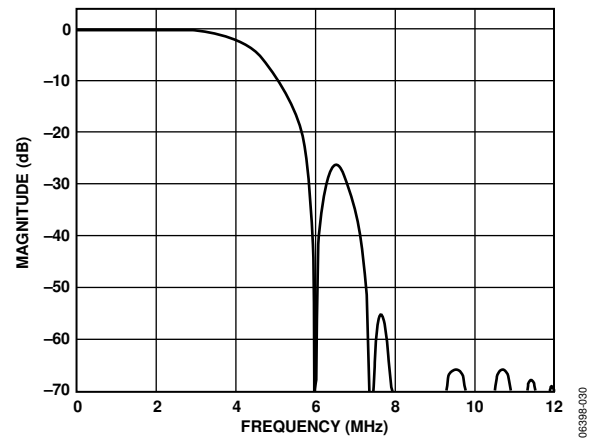


Figure 29. SD NTSC, Luma Low-Pass Filter Response

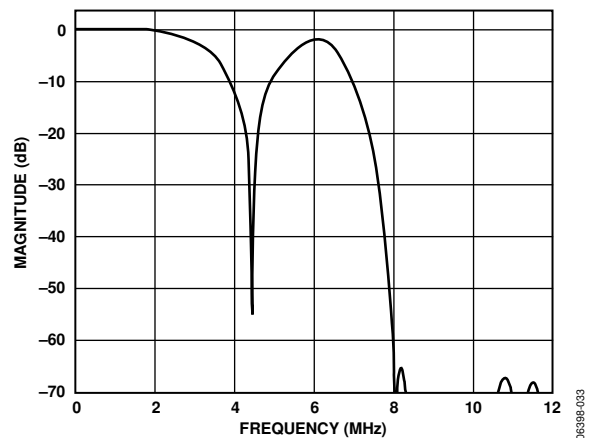


Figure 32. SD PAL, Luma Notch Filter Response